

Seung-Boo Jung

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#	Paper	IF	Citations
338	Effects of intermetallic compound on the electrical and mechanical properties of friction welded Cu/Al bimetallic joints during annealing. <i>Journal of Alloys and Compounds</i> , 2005 , 390, 212-219	5.7	241
337	The joint properties of copper by friction stir welding. <i>Materials Letters</i> , 2004 , 58, 1041-1046	3.3	200
336	Microstructural investigation of friction stir welded pure titanium. <i>Materials Letters</i> , 2005 , 59, 3315-3318	3.3	154
335	Wettability and interfacial reactions of SnAgCu/Cu and SnAgNi/Cu solder joints. <i>Journal of Alloys and Compounds</i> , 2009 , 486, 142-147	5.7	101
334	IMC morphology, interfacial reaction and joint reliability of Pb-free SnAgCu solder on electrolytic Ni BGA substrate. <i>Journal of Alloys and Compounds</i> , 2005 , 392, 247-252	5.7	96
333	Formation of intermetallic compounds in Al and Mg alloy interface during friction stir spot welding. <i>Intermetallics</i> , 2011 , 19, 125-130	3.5	92
332	Interfacial reaction and mechanical properties of eutectic Sn0.7Cu/Ni BGA solder joints during isothermal long-term aging. <i>Journal of Alloys and Compounds</i> , 2005 , 391, 82-89	5.7	91
331	Interfacial reactions and growth kinetics for intermetallic compound layer between In48Sn solder and bare Cu substrate. <i>Journal of Alloys and Compounds</i> , 2005 , 386, 151-156	5.7	85
330	Intermetallic compound layer growth at the interface between SnCuNi solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , 2004 , 381, 151-157	5.7	84
329	Growth of an intermetallic compound layer with Sn-3.5Ag-5Bi on Cu and Ni-P/Cu during aging treatment. <i>Journal of Electronic Materials</i> , 2003 , 32, 1195-1202	1.9	76
328	Effects of copper insert layer on the properties of friction welded joints between TiAl and AISI 4140 structural steel. <i>Intermetallics</i> , 2004 , 12, 671-678	3.5	75
327	Microstructures and wear property of friction stir welded AZ91 Mg/SiC particle reinforced composite. <i>Composites Science and Technology</i> , 2006 , 66, 1513-1520	8.6	74
326	Interfacial reactions and shear strengths between Sn-Ag-based Pb-free solder balls and Au/EN/Cu metallization. <i>Journal of Electronic Materials</i> , 2004 , 33, 1182-1189	1.9	72
325	Investigation of interfacial reactions between SnBi solder and Cu substrate. <i>Journal of Alloys and Compounds</i> , 2003 , 359, 202-208	5.7	70
324	Lap joint properties of FSWed dissimilar formed 5052 Al and 6061 Al alloys with different thickness. <i>Journal of Materials Science</i> , 2008 , 43, 3296-3304	4.3	68
323	Comparative Study of ENIG and ENEPIG as Surface Finishes for a Sn-Ag-Cu Solder Joint. <i>Journal of Electronic Materials</i> , 2011 , 40, 1950-1955	1.9	67
322	The Joint Characteristics of Friction Stir Welded AZ91D Magnesium Alloy. <i>Materials Transactions</i> , 2003 , 44, 917-923	1.3	67

321	Interfacial reactions between Sn0.4Cu solder and Cu substrate with or without ENIG plating layer during reflow reaction. <i>Journal of Alloys and Compounds</i> , 2005 , 396, 122-127	5.7	66
320	Reliability investigation and interfacial reaction of ball-grid-array packages using the lead-free Sn-Cu solder. <i>Journal of Electronic Materials</i> , 2004 , 33, 1190-1199	1.9	66
319	Experimental and finite element analysis of the shear speed effects on the SnAg and SnAgCu BGA solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2004 , 371, 267-276	5.3	65
318	Effect of Isothermal Aging on Ball Shear Strength in BGA Joints with Sn-3.5Ag-0.75Cu Solder. <i>Materials Transactions</i> , 2002 , 43, 1858-1863	1.3	60
317	Characteristic evaluation of electroless nickel-phosphorus deposits with different phosphorus contents. <i>Microelectronic Engineering</i> , 2007 , 84, 2552-2557	2.5	56
316	Sequential interfacial intermetallic compound formation of Cu ₆ Sn ₅ and Ni ₃ Sn ₄ between SnAgCu solder and ENEPIG substrate during a reflow process. <i>Journal of Alloys and Compounds</i> , 2011 , 509, L153-L156	5.7	55
315	Effects of Cr ₃ C ₂ on the microstructure and mechanical properties of the brazed joints between WC-Co and carbon steel. <i>International Journal of Refractory Metals and Hard Materials</i> , 2006 , 24, 215-221	4.1	55
314	Growth kinetics of Ni ₃ Sn ₄ and Ni ₃ P layer between Sn3.5Ag solder and electroless Ni substrate. <i>Journal of Alloys and Compounds</i> , 2004 , 376, 105-110	5.7	54
313	Direct Metallization of Gold Nanoparticles on a Polystyrene Bead Surface using Cationic Gold Ligands. <i>Macromolecular Rapid Communications</i> , 2007 , 28, 634-640	4.8	53
312	Interfacial reactions and shear strength on Cu and electrolytic Au/Ni metallization with Sn-Zn solder. <i>Journal of Materials Research</i> , 2006 , 21, 1590-1599	2.5	53
311	Hydrothermally Grown In-doped ZnO Nanorods on p-GaN Films for Color-tunable Heterojunction Light-emitting-diodes. <i>Scientific Reports</i> , 2015 , 5, 10410	4.9	51
310	Effect of reflow time on interfacial reaction and shear strength of Sn0.7Cu solder/Cu and electroless Ni BGA joints. <i>Journal of Alloys and Compounds</i> , 2004 , 385, 192-198	5.7	50
309	Effect of surface finish material on printed circuit board for electrochemical migration. <i>Microelectronics Reliability</i> , 2008 , 48, 652-656	1.2	47
308	The Effect of Bi Concentration on Wettability of Cu Substrate by Sn-Bi Solders. <i>Materials Transactions</i> , 2001 , 42, 751-755	1.3	46
307	Behavior of β phase (Al ₃ Mg ₂) in AA 5083 during friction stir welding. <i>Intermetallics</i> , 2013 , 35, 120-127	3.5	45
306	Effect of isothermal aging on intermetallic compound layer growth at the interface between Sn-3.5Ag-0.75Cu solder and Cu substrate. <i>Journal of Materials Science</i> , 2004 , 39, 4211-4217	4.3	45
305	Effect of aging conditions on interfacial reaction and mechanical joint strength between Sn3.0Ag0.5Cu solder and Ni UBM. <i>Materials Science and Engineering B: Solid-State Materials for Advanced Technology</i> , 2005 , 121, 204-210	3.1	42
304	Design and fabrication of screen-printed silver circuits for stretchable electronics. <i>Microelectronic Engineering</i> , 2014 , 120, 216-220	2.5	41

303	Synergistic effect of Indium and Gallium co-doping on growth behavior and physical properties of hydrothermally grown ZnO nanorods. <i>Scientific Reports</i> , 2017 , 7, 41992	4.9	40
302	Effect of Pin Shapes on Joint Characteristics of Friction Stir Spot Welded AA5J32 Sheet. <i>Materials Transactions</i> , 2010 , 51, 1028-1032	1.3	38
301	Cu ₃ Sn and Ni ₃ Sn transient liquid phase bonding for die-attach technology applications in high-temperature power electronics packaging. <i>Journal of Materials Science: Materials in Electronics</i> , 2017 , 28, 7827-7833	2.1	37
300	Effects of cerium content on wettability, microstructure and mechanical properties of Sn ₃ Ag _{0.5} Ce solder alloys. <i>Journal of Alloys and Compounds</i> , 2010 , 499, 154-159	5.7	37
299	Effect of immersion Ag surface finish on interfacial reaction and mechanical reliability of Sn ₃ .5Ag _{0.7} Cu solder joint. <i>Journal of Alloys and Compounds</i> , 2008 , 458, 200-207	5.7	37
298	Mechanical property of the epoxy-contained Sn ₃ .8Bi solder with OSP surface finish. <i>Journal of Alloys and Compounds</i> , 2014 , 615, S411-S417	5.7	36
297	Enhanced electrical and mechanical properties of silver nanoplatelet-based conductive features direct printed on a flexible substrate. <i>ACS Applied Materials & Interfaces</i> , 2013 , 5, 5908-13	9.5	34
296	Evaluation of Electrochemical Migration on Flexible Printed Circuit Boards with Different Surface Finishes. <i>Journal of Electronic Materials</i> , 2009 , 38, 902-907	1.9	34
295	Reliability evaluation of Au ₂₀ Sn flip chip solder bump fabricated by sequential electroplating method with Sn and Au. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2008 , 473, 119-125	5.3	34
294	Intermetallic compound layer formation between Sn ₃ .5 mass %Ag BGA solder ball and (Cu, immersion Au/electroless Ni ₃ /Cu) substrate. <i>Journal of Materials Science: Materials in Electronics</i> , 2003 , 14, 487-493	2.1	34
293	Void Free Friction Stir Weld Zone Of The Dissimilar 6061 Aluminum And Copper Joint By Shifting The Tool Insertion Location. <i>Materials Research Innovations</i> , 2004 , 8, 93-96	1.9	33
292	Cu-Sn Intermetallic Compound Joints for High-Temperature Power Electronics Applications. <i>Journal of Electronic Materials</i> , 2018 , 47, 430-435	1.9	32
291	Fabrication of SiCp/AA5083 composite via friction stir welding. <i>Transactions of Nonferrous Metals Society of China</i> , 2012 , 22, s634-s638	3.3	32
290	Liquid-state and solid-state interfacial reactions of fluxless-bonded Au ₂₀ Sn/ENIG solder joint. <i>Journal of Alloys and Compounds</i> , 2009 , 469, 108-115	5.7	32
289	Effect of substrate metallization on mechanical properties of Sn ₃ .5Ag BGA solder joints with multiple reflows. <i>Microelectronic Engineering</i> , 2005 , 82, 569-574	2.5	32
288	Effect of Surface Finishes on Ball Shear Strength in BGA Joints with Sn-3.5 mass%Ag Solder. <i>Materials Transactions</i> , 2002 , 43, 751-756	1.3	32
287	Effect of displacement rate on ball shear properties for Sn ₃ .7Pb and Sn ₃ .5Ag BGA solder joints during isothermal aging. <i>Microelectronics Reliability</i> , 2007 , 47, 2169-2178	1.2	31
286	Interfacial reactions and mechanical strength of Sn-3.0Ag-0.5Cu/Ni/Cu and Au-20Sn/Ni/Cu solder joints for power electronics applications. <i>Microelectronics Reliability</i> , 2017 , 71, 119-125	1.2	30

285	Effect of SiC particles on microstructure and mechanical property of friction stir processed AA6061-T4. <i>Transactions of Nonferrous Metals Society of China</i> , 2012 , 22, s614-s618	3.3	30
284	Microstructure and Mechanical Properties of Friction Stir Spot Welded Galvanized Steel. <i>Materials Transactions</i> , 2010 , 51, 1044-1050	1.3	30
283	Effect of surface finish on interfacial reactions of Cu/SnAgCu/Cu(ENIG) sandwich solder joints. <i>Journal of Alloys and Compounds</i> , 2008 , 448, 177-184	5.7	30
282	Effects of isothermal aging and temperature-humidity treatment of substrate on joint reliability of Sn3.0Ag0.5Cu/OSP-finished Cu CSP solder joint. <i>Microelectronics Reliability</i> , 2008 , 48, 1864-1874	1.2	30
281	Solid-state interfacial reactions between Sn3.5Ag0.7Cu solder and electroless Ni-immersion Au substrate during high temperature storage test. <i>Journal of Alloys and Compounds</i> , 2007 , 439, 91-96	5.7	30
280	Reliability studies of SnZn/Cu solder joints with aging treatment. <i>Journal of Alloys and Compounds</i> , 2006 , 407, 141-149	5.7	30
279	Interfacial reaction of ENIG/Sn-Ag-Cu/ENIG sandwich solder joint during isothermal aging. <i>Microelectronic Engineering</i> , 2006 , 83, 2329-2334	2.5	30
278	Evaluation of displacement rate effect in shear test of Sn3Ag0.5Cu solder bump for flip chip application. <i>Microelectronics Reliability</i> , 2006 , 46, 535-542	1.2	30
277	Effect of Microstructure on Mechanical Properties of Friction-Welded Joints between Ti and AISI 321 Stainless Steel. <i>Materials Transactions</i> , 2004 , 45, 2805-2811	1.3	30
276	Interfacial reaction and intermetallic compound formation of SnAg/ENIG and SnAg/ENEPIG solder joints. <i>Journal of Alloys and Compounds</i> , 2015 , 627, 276-280	5.7	29
275	Microstructure and mechanical property of A356 based composite by friction stir processing. <i>Transactions of Nonferrous Metals Society of China</i> , 2013 , 23, 335-340	3.3	29
274	Hybrid Friction Stir Welding of High-carbon Steel. <i>Journal of Materials Science and Technology</i> , 2011 , 27, 127-130	9.1	29
273	Characteristics of environmental factor for electrochemical migration on printed circuit board. <i>Journal of Materials Science: Materials in Electronics</i> , 2008 , 19, 952-956	2.1	29
272	Solid state interfacial reaction and joint strength of Sn7Pb solder with Ni under bump metallization in flip chip application. <i>Journal of Alloys and Compounds</i> , 2005 , 395, 80-87	5.7	28
271	Evaluation of solder joint reliability in flip-chip packages during accelerated testing. <i>Journal of Electronic Materials</i> , 2005 , 34, 1550-1557	1.9	28
270	Investigation of interfacial reaction between AuSn solder and Kovar for hermetic sealing application. <i>Microelectronic Engineering</i> , 2007 , 84, 2634-2639	2.5	27
269	Photo-induced fabrication of Ag nanowire circuitry for invisible, ultrathin, conformable pressure sensors. <i>Journal of Materials Chemistry C</i> , 2017 , 5, 9986-9994	7.1	26
268	Effects of third element and surface finish on interfacial reactions of SnAgCu (or Ni)/(Cu or ENIG) solder joints. <i>Journal of Alloys and Compounds</i> , 2010 , 506, 331-337	5.7	26

267	Interfacial reactions and joint strength of Sn ₃ Pb and Sn _{3.5} Ag solders with immersion Ag-plated Cu substrate during aging at 150 °C. <i>Journal of Materials Research</i> , 2006 , 21, 3196-3204	2.5	26
266	Interfacial reactions and joint reliability of Sn ₂ Zn solder on Cu or electrolytic Au/Ni/Cu BGA substrate. <i>Microelectronic Engineering</i> , 2005 , 82, 561-568	2.5	26
265	Effects of silver additions on the mechanical properties and resistance to thermal shock of YBa ₂ Cu ₃ O _{7-x} superconductors. <i>Cryogenics</i> , 1999 , 39, 107-113	1.8	26
264	Effect of surface finishes on electromigration reliability in eutectic Sn ₃ Bi solder joints. <i>Microelectronic Engineering</i> , 2014 , 120, 77-84	2.5	25
263	Mechanical reliability of Sn-rich Au ₃ Ni flip chip solder joints fabricated by sequential electroplating method. <i>Microelectronics Reliability</i> , 2008 , 48, 1857-1863	1.2	25
262	Drop Reliability of Epoxy-contained Sn-58 wt.%Bi Solder Joint with ENIG and ENEPIG Surface Finish Under Temperature and Humidity Test. <i>Journal of Electronic Materials</i> , 2016 , 45, 3651-3658	1.9	24
261	Reliability analysis of Au ₃ Ni flip-chip solder bump fabricated by co-electroplating. <i>Journal of Materials Research</i> , 2007 , 22, 1219-1229	2.5	24
260	Characterization of the shear test method with low melting point In ₃ Sn solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2005 , 397, 145-152	5.3	24
259	Effect of reflow numbers on the interfacial reaction and shear strength of flip chip solder joints. <i>Journal of Alloys and Compounds</i> , 2008 , 458, 253-260	5.7	23
258	Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. <i>Microelectronic Engineering</i> , 2008 , 85, 1967-1970	2.5	23
257	Effects of reflow and cooling conditions on interfacial reaction and IMC morphology of Sn ₃ Cu/Ni solder joint. <i>Journal of Alloys and Compounds</i> , 2006 , 415, 56-61	5.7	23
256	Electrically and mechanically enhanced Ag nanowires-colorless polyimide composite electrode for flexible capacitive sensor. <i>Applied Surface Science</i> , 2016 , 380, 223-228	6.7	22
255	Electrochemical migration behavior of silver nanopaste screen-printed for flexible and printable electronics. <i>Current Applied Physics</i> , 2013 , 13, S190-S194	2.6	22
254	Failure mechanism of Pb-bearing and Pb-free solder joints under high-speed shear loading. <i>Metals and Materials International</i> , 2010 , 16, 7-12	2.4	22
253	Characterization of direct patterned Ag circuits for RF application. <i>Microelectronic Engineering</i> , 2010 , 87, 379-382	2.5	22
252	Effect of laminating parameters on the adhesion property of flexible copper clad laminate with adhesive layer. <i>International Journal of Adhesion and Adhesives</i> , 2010 , 30, 30-35	3.4	22
251	Effect of boron content in electroless Ni ₃ B layer on plating layer properties and soldering characteristics with Sn ₃ Ag solder. <i>Journal of Alloys and Compounds</i> , 2008 , 466, 73-79	5.7	22
250	The characteristics of Cu nanopaste sintered by atmospheric-pressure plasma. <i>Microelectronic Engineering</i> , 2013 , 107, 121-124	2.5	21

249	Effect of multiple reflows on interfacial reaction and shear strength of SnAg electroplated solder bumps for flip chip package. <i>Microelectronic Engineering</i> , 2010 , 87, 517-521	2.5	21
248	Reliability of adhesive interconnections for application in display module. <i>Microelectronic Engineering</i> , 2007 , 84, 2691-2696	2.5	21
247	Effects of bonding pressure on the thermo-mechanical reliability of ACF interconnection. <i>Microelectronic Engineering</i> , 2006 , 83, 2335-2340	2.5	21
246	Electrochemical migration of directly printed Ag electrodes using Ag paste with epoxy binder. <i>Microelectronic Engineering</i> , 2013 , 103, 1-6	2.5	20
245	Microstructure, Electrical Properties, and Electrochemical Migration of a Directly Printed Ag Pattern. <i>Journal of Electronic Materials</i> , 2011 , 40, 35-41	1.9	20
244	Comparison of Interfacial Stability of Pb-Free Solders (Sn ₃ .5Ag, Sn ₃ .5Ag ₀ .7Cu, and Sn ₀ .7Cu) on ENIG-Plated Cu During Aging. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2010 , 33, 64-70		20
243	AuSn flip-chip solder bump for microelectronic and optoelectronic applications. <i>Microsystem Technologies</i> , 2007 , 13, 1463-1469	1.7	20
242	Effect of high-speed loading conditions on the fracture mode of the BGA solder joint. <i>Microelectronics Reliability</i> , 2008 , 48, 1882-1889	1.2	20
241	Reexamination of the solder ball shear test for evaluation of the mechanical joint strength. <i>International Journal of Solids and Structures</i> , 2006 , 43, 1928-1945	3.1	20
240	Mechanical properties of copper to titanium joined by friction welding. <i>Journal of Materials Science</i> , 2003 , 38, 1281-1287	4.3	20
239	Die-attach for power devices using the Ag sintering process: Interfacial microstructure and mechanical strength. <i>Metals and Materials International</i> , 2017 , 23, 958-963	2.4	19
238	Electrical properties and electrochemical migration characteristics of directly printed Ag patterns with various sintering conditions. <i>Microelectronics Reliability</i> , 2014 , 54, 410-416	1.2	19
237	Effects of Ag content on the reliability of LED package component with SnBiAg solder. <i>Journal of Materials Science: Materials in Electronics</i> , 2015 , 26, 8707-8713	2.1	19
236	Enhancing Adhesion of Screen-Printed Silver Nanopaste Films. <i>Advanced Materials Interfaces</i> , 2015 , 2, 1500283	4.6	19
235	Effect of Pd Addition in ENIG Surface Finish on Drop Reliability of Sn-Ag-Cu Solder Joint. <i>Materials Transactions</i> , 2011 , 52, 1553-1559	1.3	19
234	Interfacial reaction between AuSn solder and Au/Ni-metallized Kovar. <i>Journal of Materials Science: Materials in Electronics</i> , 2011 , 22, 84-90	2.1	19
233	Adhesion characteristics of Cu/NiCr/polyimide flexible copper clad laminates according to Ni:Cr ratio and Cu electroplating layer thickness. <i>Journal of Materials Science: Materials in Electronics</i> , 2009 , 20, 885-890	2.1	19
232	Characterization of Interfacial Reaction Layers Formed Between Sn-3.5Ag Solder and Electroless Ni-Immersion Au-Plated Cu Substrates. <i>Journal of Electronic Materials</i> , 2008 , 37, 84-89	1.9	19

231	High temperature reliability and interfacial reaction of eutectic Sn _{0.7} Cu/Ni solder joints during isothermal aging. <i>Microelectronics Reliability</i> , 2006 , 46, 905-914	1.2	19
230	Reliability of In-48Sn solder/Au/Ni/Cu BGA packages during reflow process. <i>Journal of Electronic Materials</i> , 2005 , 34, 1565-1572	1.9	19
229	Effect of isothermal aging on the interfacial reactions between Sn _{0.4} Cu solder and Cu substrate with or without ENIG plating layer. <i>Surface and Coatings Technology</i> , 2006 , 200, 4440-4447	4.4	18
228	Friction welding of TiAl and AISI4140. <i>Journal of Materials Science</i> , 2004 , 39, 1125-1128	4.3	18
227	Flexibility of silver conductive circuits screen-printed on a polyimide substrate. <i>Journal of Nanoscience and Nanotechnology</i> , 2011 , 11, 1493-8	1.3	17
226	Structure–Properties Relations in Friction Stir Spot Welded Low Carbon Steel Sheets for Light Weight Automobile Body. <i>Materials Transactions</i> , 2010 , 51, 399-403	1.3	17
225	Analysis of Failure Mechanism in Anisotropic Conductive and Non-Conductive Film Interconnections. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008 , 31, 65-73		17
224	Reliability of Conductive Adhesives as a Pb-free Alternative in Flip-Chip Applications. <i>Journal of Electronic Materials</i> , 2008 , 37, 9-16	1.9	17
223	Electromigration behaviors of Sn58%Bi solder containing Ag-coated MWCNTs with OSP surface finished PCB. <i>Journal of Alloys and Compounds</i> , 2019 , 775, 581-588	5.7	17
222	Effect of Sintering Conditions on the Mechanical Strength of Cu-Sintered Joints for High-Power Applications. <i>Materials</i> , 2018 , 11,	3.5	17
221	Fabrication of the hybrid Ag paste combined by Ag nanoparticle and micro Ag flake and its flexibility. <i>Journal of Alloys and Compounds</i> , 2017 , 699, 1186-1191	5.7	16
220	A UV-responsive pressure sensitive adhesive for damage-free fabrication of an ultrathin imperceptible mechanical sensor with ultrahigh optical transparency. <i>Journal of Materials Chemistry A</i> , 2019 , 7, 22588-22595	13	16
219	Fabrication of Ag-MWNT nanocomposite paste for high-power LED package. <i>Current Applied Physics</i> , 2015 , 15, S36-S41	2.6	16
218	Fabrication and adhesion strength of Cu/NiCr/polyimide films for flexible printed circuits. <i>Microelectronic Engineering</i> , 2011 , 88, 1024-1027	2.5	16
217	Failure behaviors of BGA solder joints under various loading conditions of high-speed shear test. <i>Journal of Materials Science: Materials in Electronics</i> , 2009 , 20, 17-24	2.1	15
216	Effect of thermal treatment on adhesion strength of Cu/NiCr/polyimide flexible copper clad laminate fabricated by roll-to-roll process. <i>Microelectronic Engineering</i> , 2011 , 88, 718-723	2.5	15
215	Evaluation of solder joint reliability in flip chip package under thermal shock test. <i>Thin Solid Films</i> , 2006 , 504, 426-430	2.2	15
214	Mechanical properties of Sn-58 wt%Bi solder containing Ag-decorated MWCNT with thermal aging tests. <i>Journal of Alloys and Compounds</i> , 2020 , 820, 153077	5.7	15

213	Evaluation of the Bondability of the Epoxy-Enhanced Sn-58Bi Solder with ENIG and ENEPIG Surface Finishes. <i>Journal of Electronic Materials</i> , 2015 , 44, 4637-4645	1.9	14
212	Effects of Aging Treatment on Mechanical Properties of Sn-58Bi Epoxy Solder on ENEPIG-Surface-Finished PCB. <i>Journal of Electronic Materials</i> , 2016 , 45, 5895-5903	1.9	14
211	Evaluation of drop reliability of Sn37Pb solder/Cu joints using a high speed lap-shear test. <i>Microelectronic Engineering</i> , 2012 , 91, 147-153	2.5	14
210	Effects of sintering conditions on microstructure and characteristics of screen-printed Ag thin film. <i>Electronic Materials Letters</i> , 2012 , 8, 309-314	2.9	14
209	Effect of adding Ce on interfacial reactions between SnAg solder and Cu. <i>Journal of Materials Science: Materials in Electronics</i> , 2011 , 22, 745-750	2.1	14
208	Electromigration Behavior in Sn-37Pb and Sn-3.0Ag-0.5Cu Flip-Chip Solder Joints under High Current Density. <i>Journal of Electronic Materials</i> , 2009 , 38, 70-77	1.9	14
207	Mechanical Property Evaluation of Sn-3.0Ag-0.5Cu BGA Solder Joints Using High-Speed Ball Shear Test. <i>Journal of Electronic Materials</i> , 2009 , 38, 2489-2495	1.9	14
206	Application of Underfill for Flip-Chip Package Using Ultrasonic Bonding. <i>Japanese Journal of Applied Physics</i> , 2008 , 47, 4257-4261	1.4	14
205	Investigation of interfacial reaction and joint reliability between eutectic Sn3.5Ag solder and ENIG-plated Cu substrate during high temperature storage test. <i>Journal of Materials Science: Materials in Electronics</i> , 2007 , 18, 559-567	2.1	14
204	Mechanical and Electrical Properties of Cu/Sn-3.5Ag/Cu Ball Grid Array (BGA) Solder Joints after Multiple Reflows. <i>Journal of Electronic Materials</i> , 2008 , 37, 118-124	1.9	14
203	Investigations of the test parameters and bump structures in the shear test of flip chip solder bump. <i>Thin Solid Films</i> , 2006 , 504, 405-409	2.2	14
202	Bonding of power device to ceramic substrate using Sn-coated Cu micro paste for high-temperature applications. <i>Applied Surface Science</i> , 2020 , 515, 146060	6.7	13
201	The microstructures and mechanical properties of friction stir welded AZ31 with CaO Mg alloys. <i>Journal of Alloys and Compounds</i> , 2013 , 554, 162-168	5.7	13
200	Effect of Ni-Cr seed layer thickness on the adhesion characteristics of flexible copper clad laminates fabricated using a roll-to-roll process. <i>Metals and Materials International</i> , 2010 , 16, 779-784	2.4	13
199	Initial interfacial reaction layers formed in Sn3.5Ag solder/electroless Ni plated Cu substrate system. <i>Journal of Materials Research</i> , 2008 , 23, 2195-2201	2.5	13
198	Effect of surface finish of substrate on mechanical reliability of In-48Sn solder joints in MOEMS package. <i>Microsystem Technologies</i> , 2007 , 13, 1567-1573	1.7	13
197	Microstructural evolution and interfacial reactions of fluxless-bonded Au-20Sn/Cu solder joint during reflow and aging. <i>Journal of Materials Research</i> , 2007 , 22, 2817-2824	2.5	13
196	Microstructure and mechanical properties of a B4C particle-reinforced Cu matrix composite fabricated by friction stir welding. <i>Journal of Alloys and Compounds</i> , 2017 , 693, 688-691	5.7	12

195	Microstructure and adhesion characteristics of a silver nanopaste screen-printed on Si substrate. <i>Nanoscale Research Letters</i> , 2012 , 7, 49	5	12
194	Effect of Ni-Cr Layer on Adhesion Strength of Flexible Copper Clad Laminate. <i>Journal of Electronic Materials</i> , 2009 , 38, 46-53	1.9	12
193	Reliability of Au bump flip chip packages with adhesive materials using four-point bending test. <i>International Journal of Adhesion and Adhesives</i> , 2009 , 29, 650-655	3.4	12
192	Fabrication of two-layer flexible copper clad laminate by electroless-Cu plating on surface modified polyimide. <i>Transactions of Nonferrous Metals Society of China</i> , 2009 , 19, 970-974	3.3	12
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